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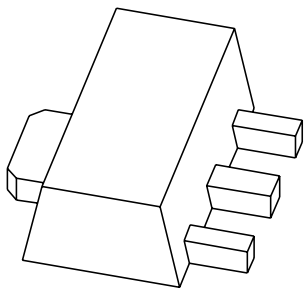
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Kind regards,

Team Nexperia

# DATA SHEET



**PBSS5520X**

20 V, 5 A

PNP low  $V_{CEsat}$  (BISS) transistor

Product data sheet  
Supersedes data of 2004 Jun 23

2004 Nov 08

**20 V, 5 A**  
**PNP low  $V_{CEsat}$  (BISS) transistor**

**PBSS5520X**

**FEATURES**

- High  $h_{FE}$  and low  $V_{CEsat}$  at high current operation
- High collector current  $I_C$ : 5 A
- High efficiency leading to less heat generation.

**APPLICATIONS**

- Medium power peripheral drivers (e.g. fans and motors)
- Strobe flash units for digital still cameras and mobile phones
- Power switch for LAN and ADSL systems
- Medium power DC-to-DC conversion
- Battery chargers
- Supply line switching.

**DESCRIPTION**

PNP low  $V_{CEsat}$  (BISS) transistor in a SOT89 (SC-62) plastic package.  
 NPN complement: PBSS4520X.

**MARKING**

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PBSS5520X	*1K

**Note**

- \* = p: made in Hong Kong.  
 \* = t: made in Malaysia.  
 \* = W: made in China.

**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	UNIT
$V_{CEO}$	collector-emitter voltage	-20	V
$I_C$	collector current (DC)	-5	A
$I_{CM}$	peak collector current	-10	A
$R_{CEsat}$	equivalent on-resistance	54	m $\Omega$

**PINNING**

PIN	DESCRIPTION
1	emitter
2	collector
3	base

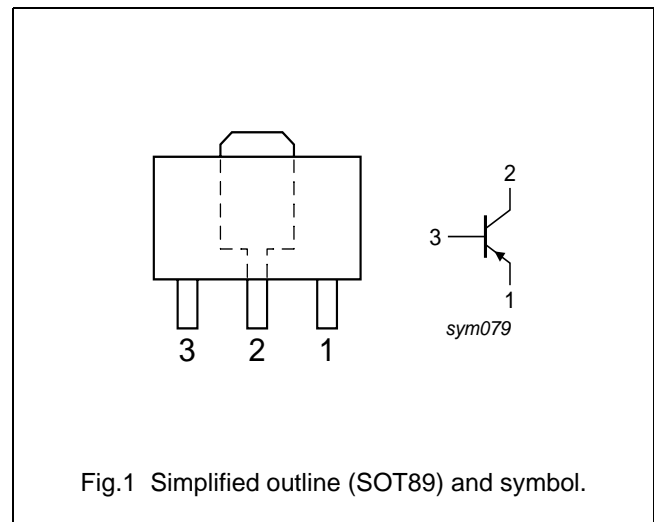


Fig.1 Simplified outline (SOT89) and symbol.

**ORDERING INFORMATION**

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PBSS5520X	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89

20 V, 5 A  
PNP low  $V_{CEsat}$  (BISS) transistor

PBSS5520X

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

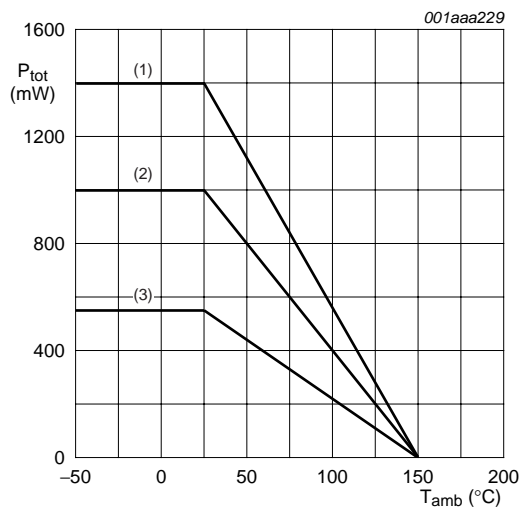
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	–20	V
$V_{CEO}$	collector-emitter voltage	open base	–	–20	V
$V_{EBO}$	emitter-base voltage	open collector	–	–5	V
$I_C$	collector current (DC)		–	–5	A
$I_{CM}$	peak collector current	$t_p \leq 1$ ms	–	–10	A
$I_{CRP}$	repetitive peak collector current	notes 1 and 2	–	–6.5	A
$I_B$	base current (DC)		–	–1	A
$I_{BM}$	peak base current	$t_p \leq 1$ ms	–	–2	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C notes 1 and 2 note 2 note 3 note 4 note 5	–	2.5 0.55 1 1.4 1.6	W W W W W
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C
$T_{amb}$	ambient temperature		–65	+150	°C

**Notes**

1. Operated under pulsed conditions; pulse width  $t_p \leq 10$  ms; duty cycle  $\delta \leq 0.2$ .
2. Device mounted on a printed-circuit board, single-sided copper, tin-plated, standard footprint.
3. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
4. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.
5. Device mounted on a 7 cm<sup>2</sup> ceramic printed-circuit board, 1 cm<sup>2</sup> single-sided copper, tin-plated.

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- (1) FR4 PCB; 6 cm<sup>2</sup> mounting pad for collector.
- (2) FR4 PCB; 1 cm<sup>2</sup> mounting pad for collector.
- (3) FR4 PCB; standard footprint.

Fig.2 Power derating curves.

20 V, 5 A  
PNP low  $V_{CEsat}$  (BISS) transistor

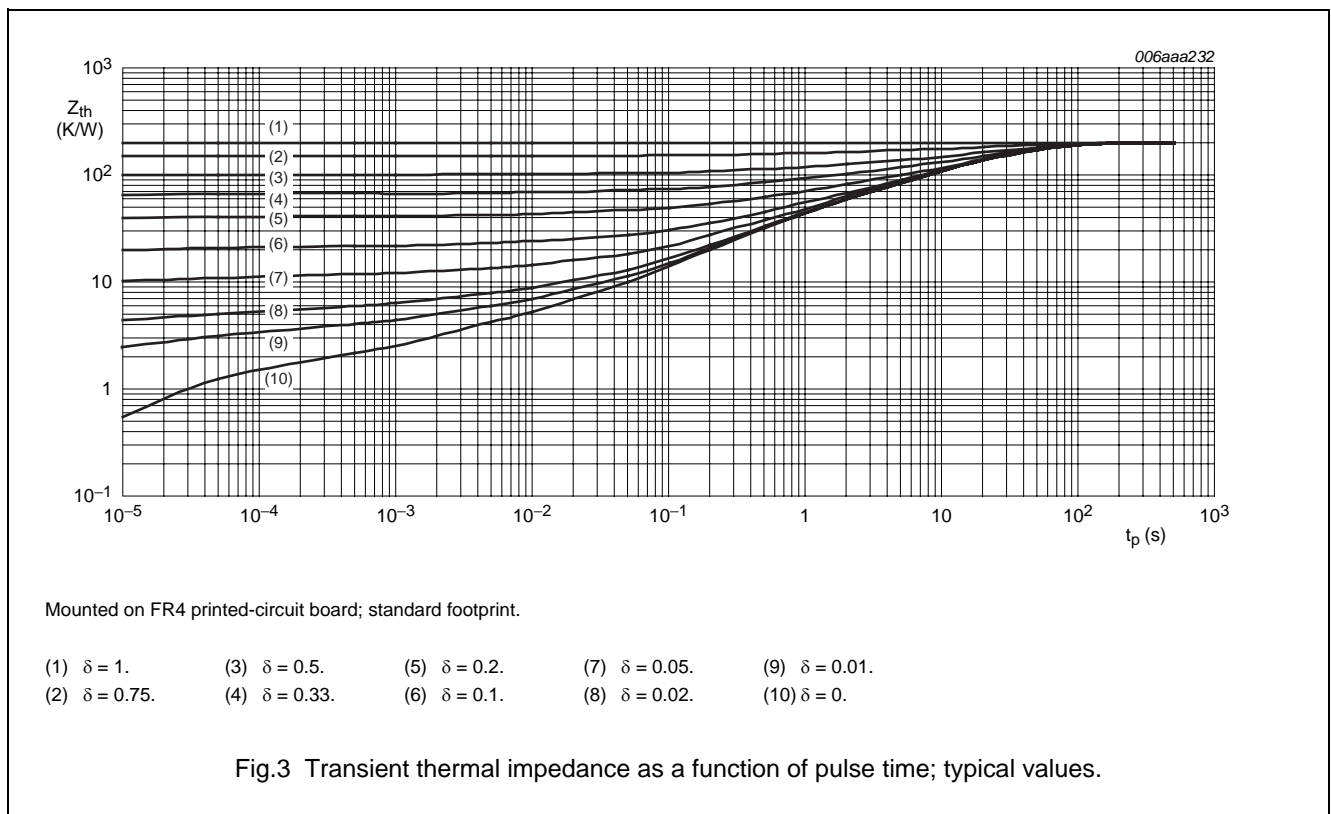
PBSS5520X

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		
		notes 1 and 2	50	K/W
		note 2	225	K/W
		note 3	125	K/W
		note 4	90	K/W
		note 5	80	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point		16	K/W

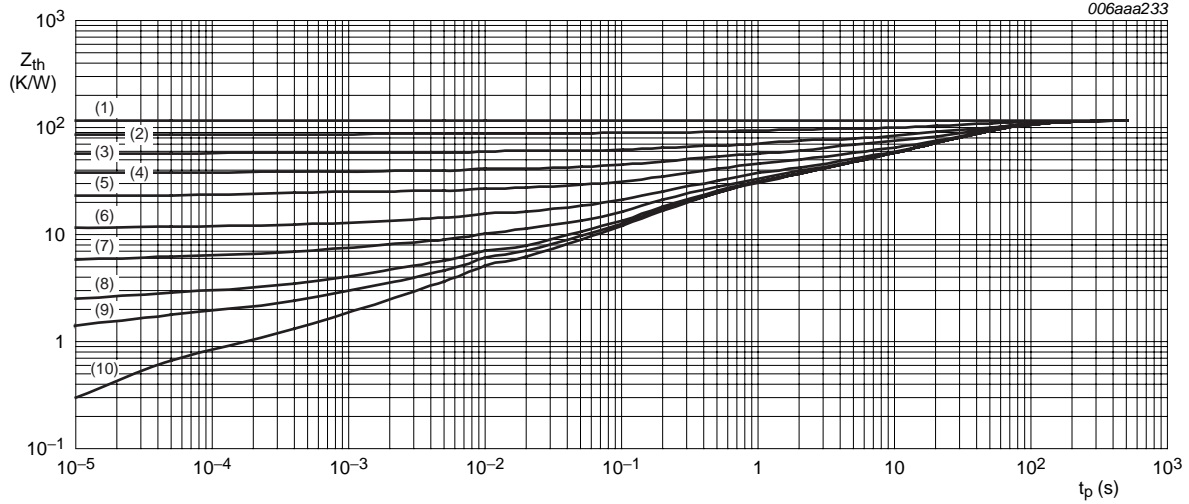
**Notes**

1. Operated under pulsed conditions; pulse width  $t_p \leq 10$  ms; duty cycle  $\delta \leq 0.2$ .
2. Device mounted on a printed-circuit board, single-sided copper, tin-plated, standard footprint.
3. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
4. Device mounted on a printed-circuit board, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.
5. Device mounted on a 7 cm<sup>2</sup> ceramic printed-circuit board, 1 cm<sup>2</sup> single-sided copper, tin-plated.



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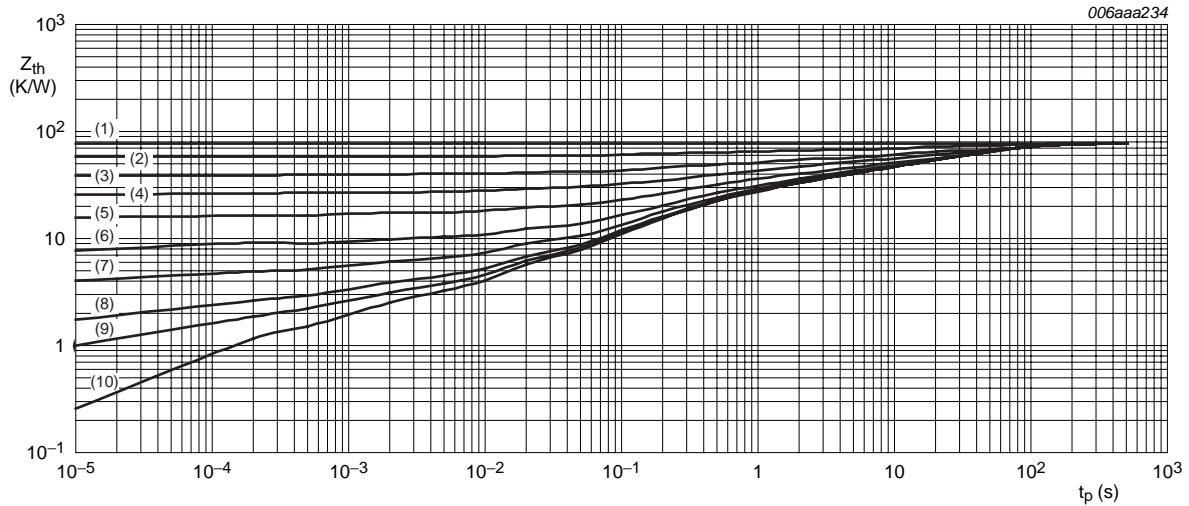
PBSS5520X



Mounted on FR4 printed-circuit board; mounting pad for collector 1 cm<sup>2</sup>.

- |                      |                      |                     |                      |                      |
|----------------------|----------------------|---------------------|----------------------|----------------------|
| (1) $\delta = 1.$    | (3) $\delta = 0.5.$  | (5) $\delta = 0.2.$ | (7) $\delta = 0.05.$ | (9) $\delta = 0.01.$ |
| (2) $\delta = 0.75.$ | (4) $\delta = 0.33.$ | (6) $\delta = 0.1.$ | (8) $\delta = 0.02.$ | (10) $\delta = 0.$   |

Fig.4 Transient thermal impedance as a function of pulse time; typical values.



Mounted on FR4 printed-circuit board; mounting pad for collector 6 cm<sup>2</sup>.

- |                      |                      |                     |                      |                      |
|----------------------|----------------------|---------------------|----------------------|----------------------|
| (1) $\delta = 1.$    | (3) $\delta = 0.5.$  | (5) $\delta = 0.2.$ | (7) $\delta = 0.05.$ | (9) $\delta = 0.01.$ |
| (2) $\delta = 0.75.$ | (4) $\delta = 0.33.$ | (6) $\delta = 0.1.$ | (8) $\delta = 0.02.$ | (10) $\delta = 0.$   |

Fig.5 Transient thermal impedance as a function of pulse time; typical values.

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**CHARACTERISTICS** $T_{amb} = 25\text{ °C}$  unless otherwise specified.

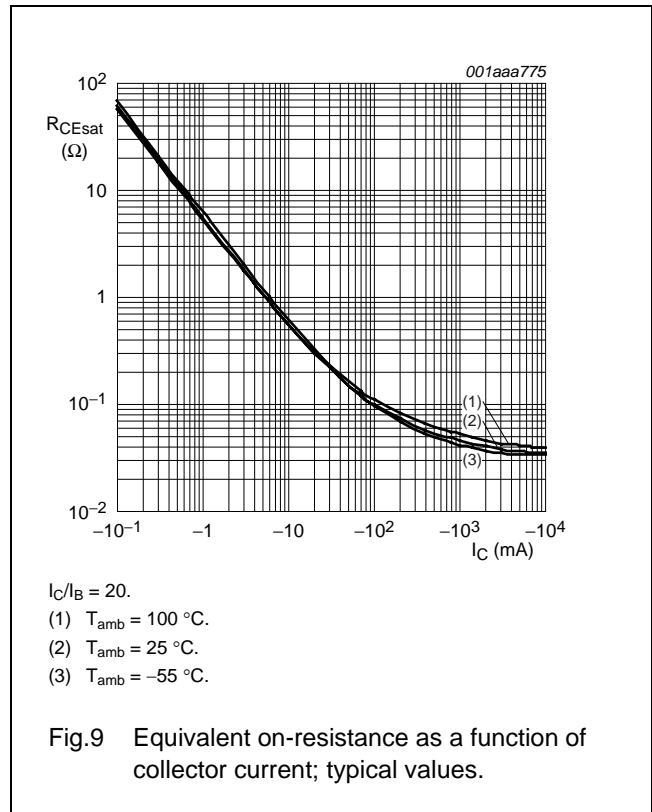
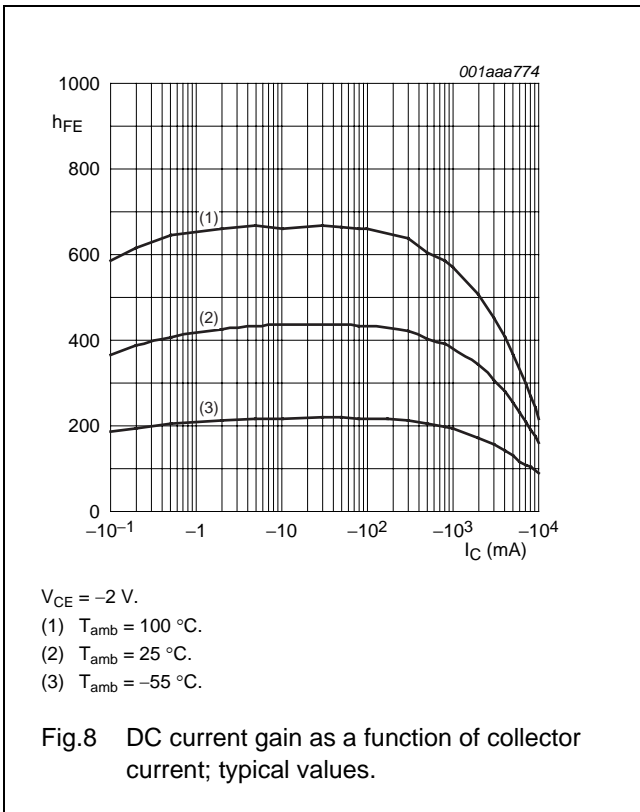
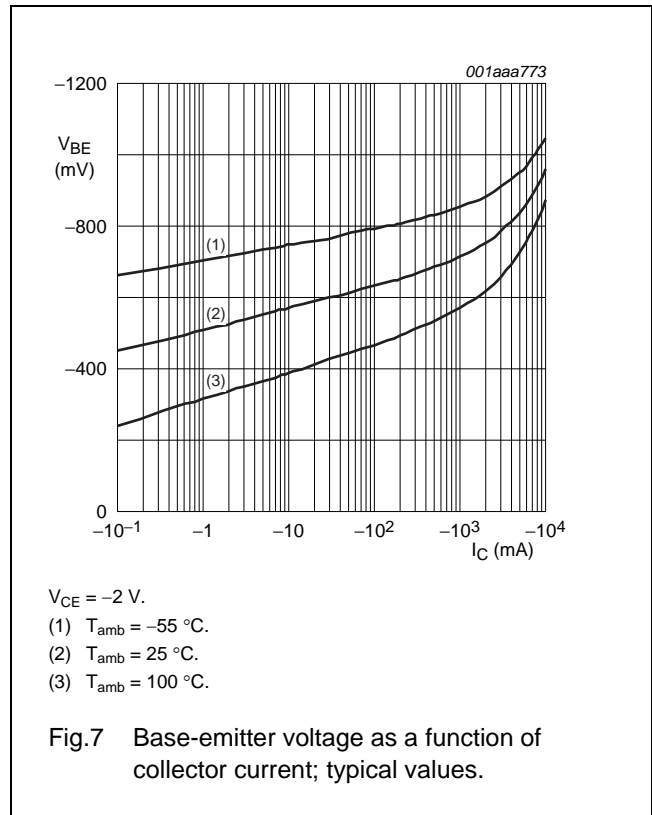
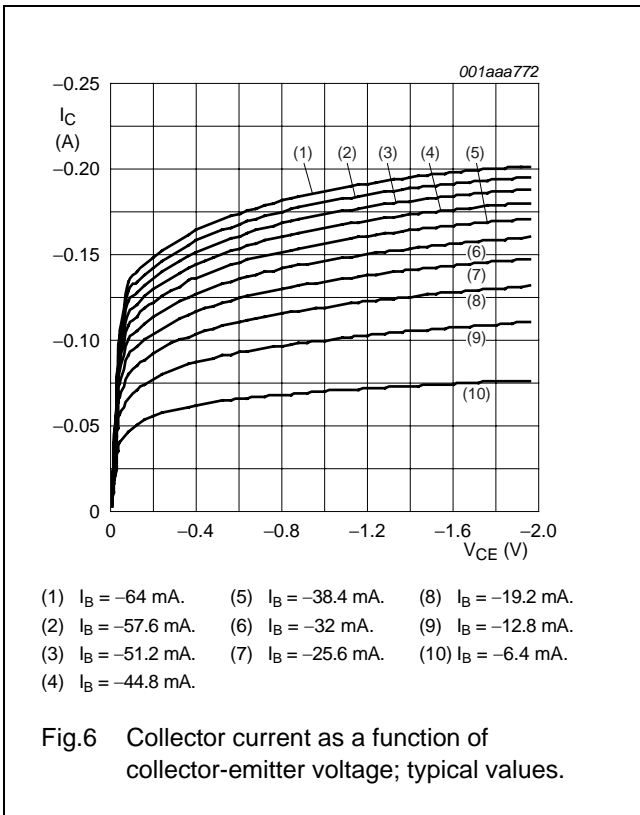
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -20\text{ V}; I_E = 0\text{ A}$	–	–	–100	nA
		$V_{CB} = -20\text{ V}; I_E = 0\text{ A}; T_J = 150\text{ °C}$	–	–	–50	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	–	–	–100	nA
$I_{CES}$	collector-emitter cut-off current	$V_{CE} = -20\text{ V}; V_{BE} = 0\text{ V}$	–	–	–100	nA
$h_{FE}$	DC current gain	$V_{CE} = -2\text{ V}$				
		$I_C = -0.5\text{ A}; \text{note 1}$	300	430	–	
		$I_C = -1\text{ A}; \text{note 1}$	275	400	–	
		$I_C = -2\text{ A}; \text{note 1}$	250	360	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -0.5\text{ A}; I_B = -5\text{ mA}$	–	–45	–70	mV
		$I_C = -1\text{ A}; I_B = -10\text{ mA}$	–	–70	–110	mV
		$I_C = -2.5\text{ A}; I_B = -125\text{ mA}; \text{note 1}$	–	–100	–150	mV
		$I_C = -4\text{ A}; I_B = -200\text{ mA}; \text{note 1}$	–	–150	–230	mV
		$I_C = -5\text{ A}; I_B = -500\text{ mA}; \text{note 1}$	–	–170	–270	mV
$R_{CEsat}$	equivalent on-resistance	$I_C = -5\text{ A}; I_B = -500\text{ mA}; \text{note 1}$	–	34	54	$\text{m}\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -4\text{ A}; I_B = -200\text{ mA}; \text{note 1}$	–	–0.9	–1.05	V
		$I_C = -5\text{ A}; I_B = -500\text{ mA}; \text{note 1}$	–	–0.96	–1.1	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -2\text{ A}$	–	–0.74	–0.85	V
$f_T$	transition frequency	$I_C = -100\text{ mA}; V_{CE} = -10\text{ V};$ $f = 100\text{ MHz}$	80	100	–	MHz
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_e = 0\text{ A};$ $f = 1\text{ MHz}$	–	130	150	pF

**Note**1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .



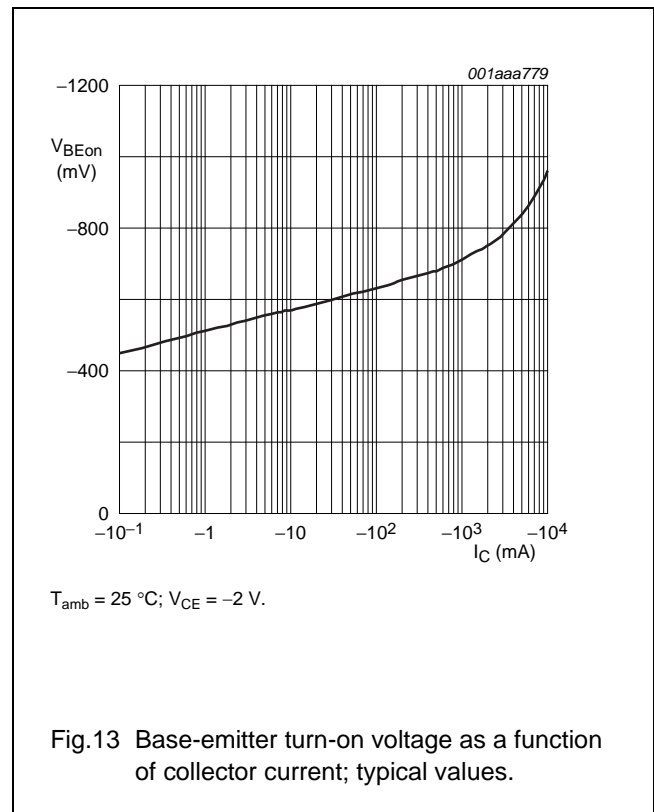
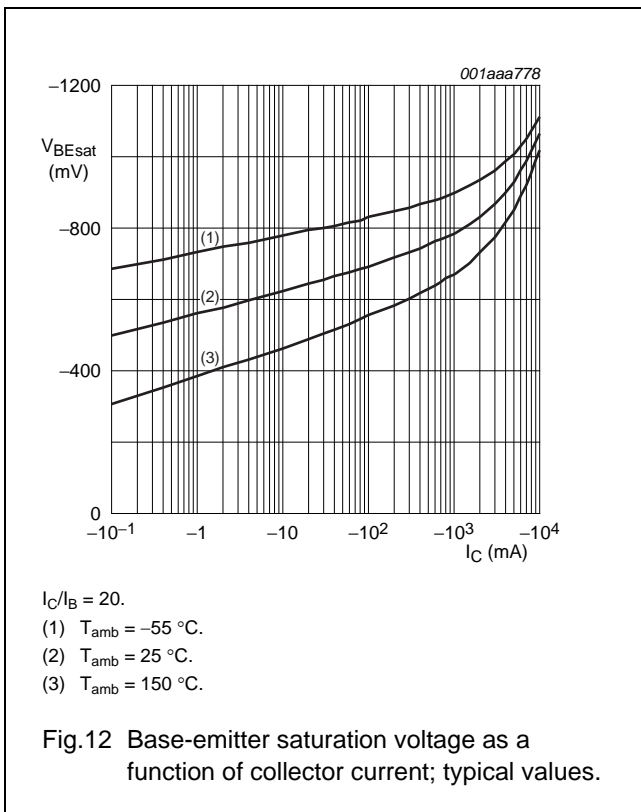
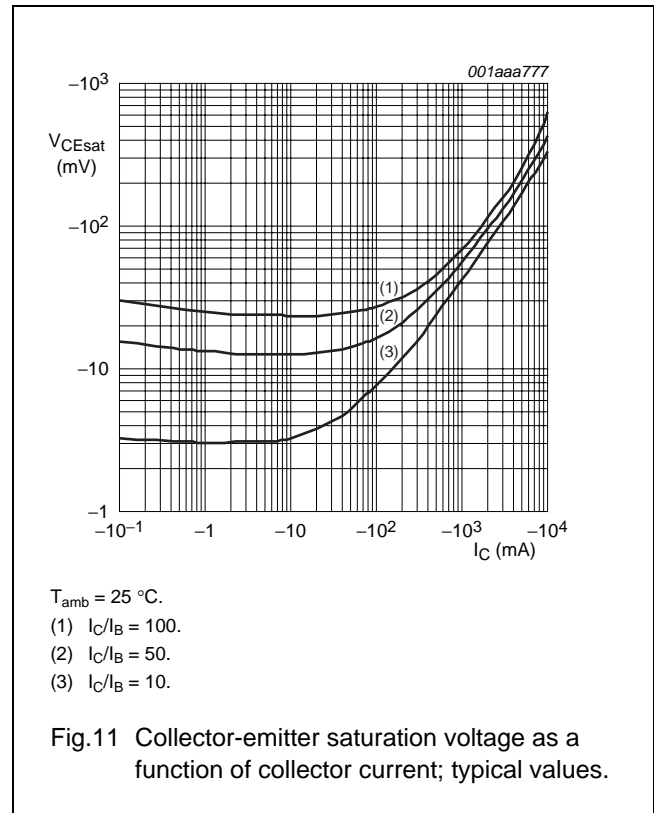
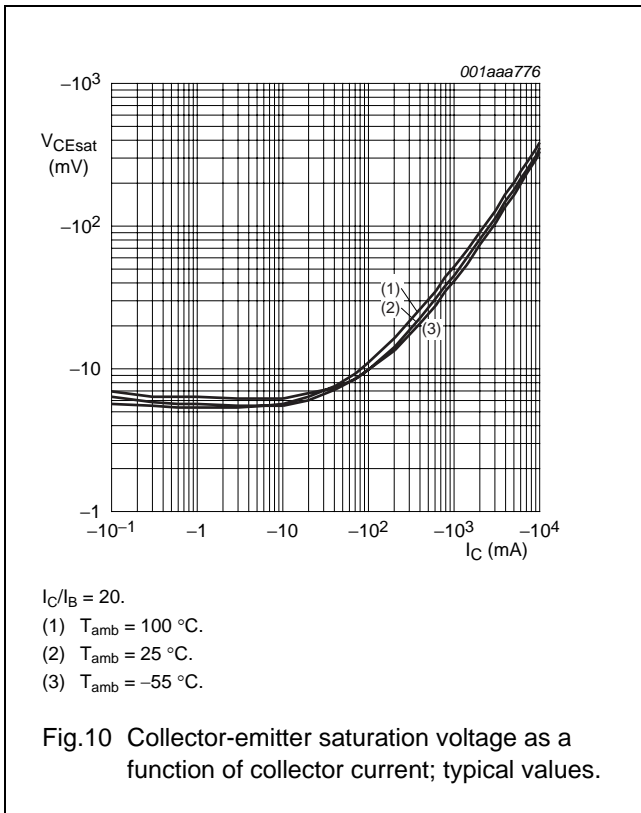
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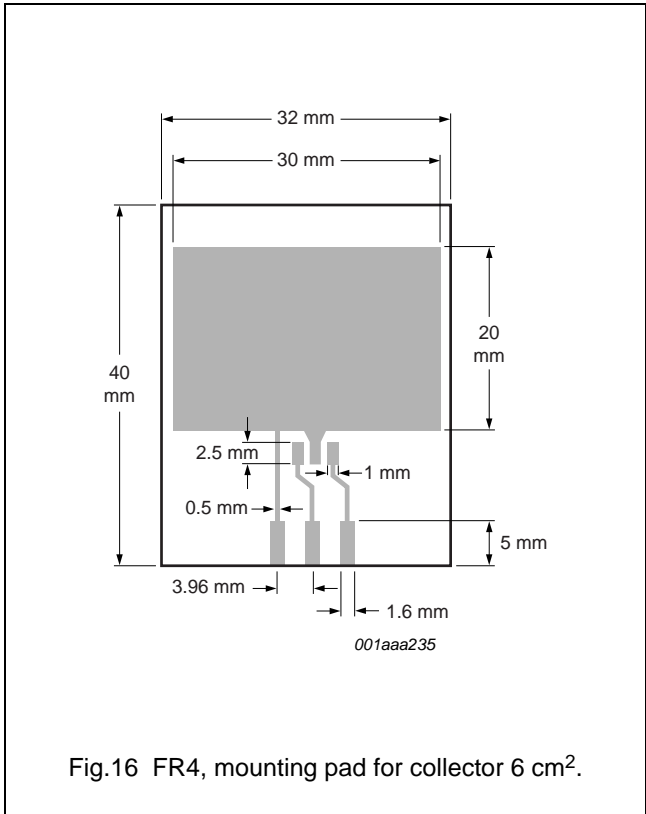
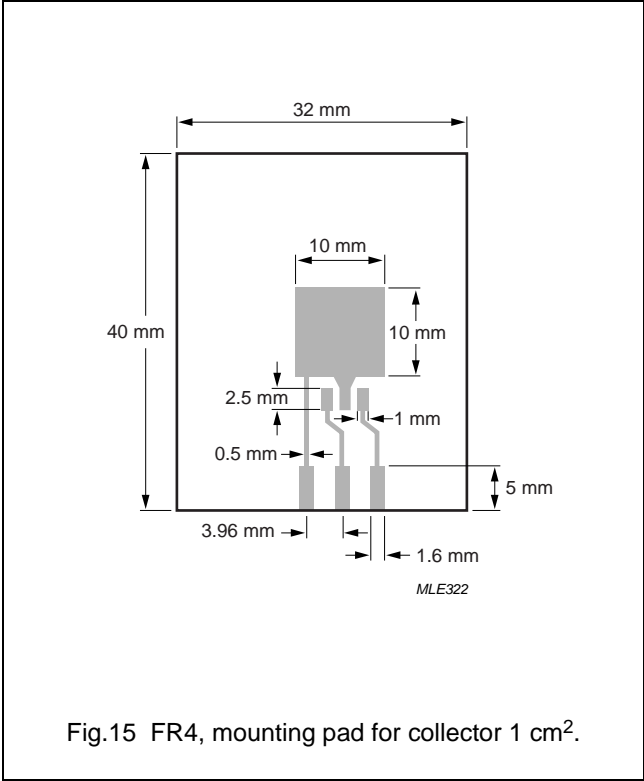
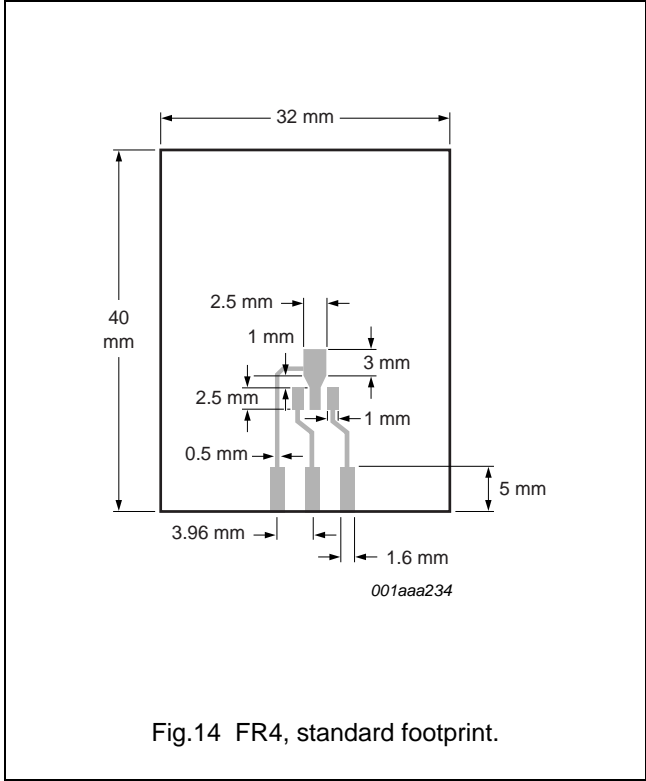
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Reference mounting conditions



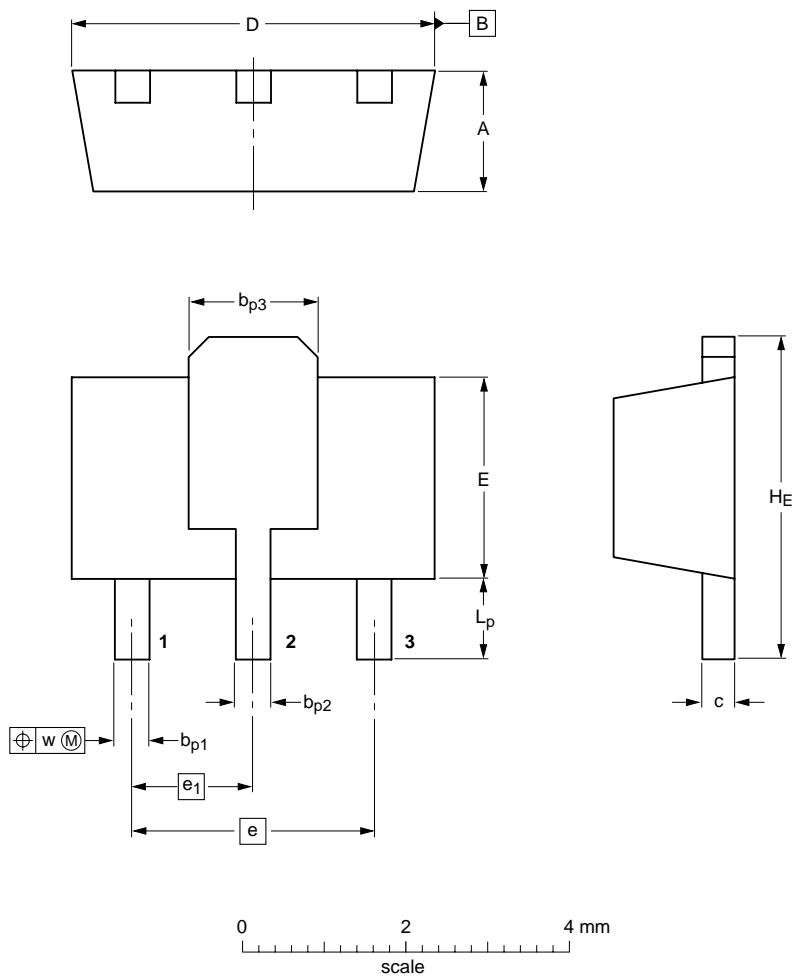
20 V, 5 A  
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PBSS5520X

PACKAGE OUTLINE

Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



DIMENSIONS (mm are the original dimensions)

UNIT	A	bp1	bp2	bp3	c	D	E	e	e1	HE	Lp	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.23	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	1.2 0.8	0.13

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT89		TO-243	SC-62		04-08-03 06-03-16

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**DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# ***NXP Semiconductors***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

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